FSB-860B

Thermal Image Analysis Report

Report No: 04I080002

Release Date: Dec. 31, 2004

2004-12-31	Wenyuan Yang	Andrew KU
Issue Stamp	**Manager**	**Test Engineer**

Thermal Image Analysis

Ⅰ. **Model Name:** **FSB-860B**

Ⅱ. **Description:** Full-size PICMG CPU Card. Socket 478 Pentium 4 Processor CPU Card. with VGA / two Ethernet. /Audio/CFD/5USBs/ATX

Ⅲ. **Date:** **Dec. 31, 2004**

Ⅳ. **Measure Site:** **AAEON QE Dept.**

Ⅴ. **Issued by:** **Andrew Ku**

Ⅵ.**Equipment:**

1. TVS-100 series by NIPPON AVIONICS CO., LTD.

Ⅶ. **Simulation Environment:**

- **Temperature: 20.8 degrees C**
- **System Configuration : FSB-860B A0.2(BIOS ver : 1.0)**
  CPU: Intel Pentium 4 / 3.06GHz / FSB 533MHz
  Memory: KINGMAX KDL684J44A-60 (DDR-333) / 256MB
  HDD: Seagate ST31276A
- **Application Software: Windows 2000 run HCT9.5**
- **Take Picture Time: Power on 2 hours after**

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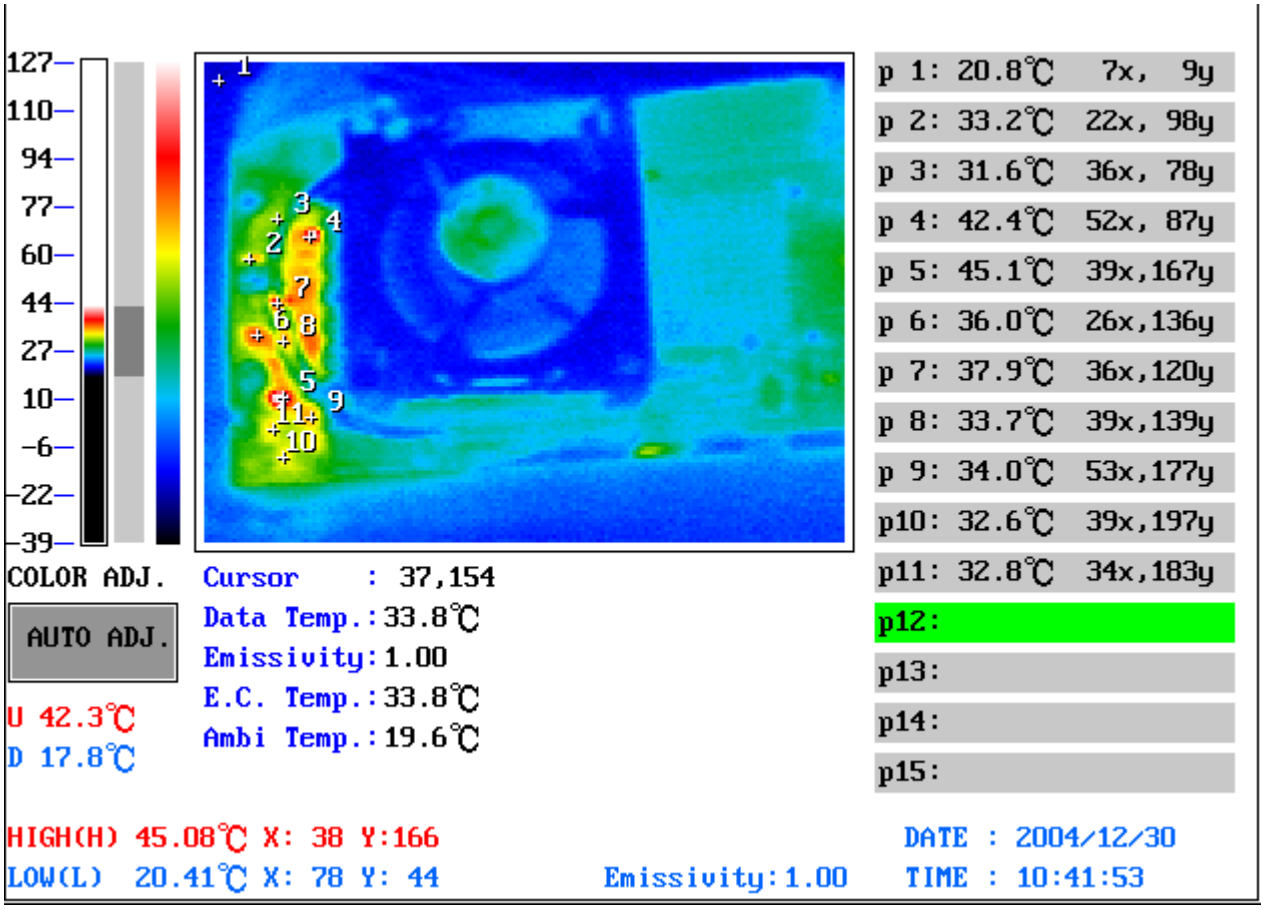
Thermal Image Analysis

Temperature Profile Test:

Component Side – 1:



Point	Position	Describe	Ts	Tm	Note
1		The Room Temperature		20.8℃	
2	Q7	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD414		33.2℃	
3	Q8	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD414		31.6℃	
4	U12	IC.SMD.SOIC 8Pin MOSFET Drivers.INTERSIL.HIP6601B		42.4℃	
5	U14	IC.SMD.SOIC 8Pin MOSFET Drivers.INTERSIL.HIP6601B		45.1℃	
6	Q9	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD412		36.0℃	
7	U13	IC.SMD.SOIC 8Pin MOSFET Drivers.INTERSIL.HIP6601B		37.9℃	
8	Q11	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD414		33.7℃	
9	Q16	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD414		34.0℃	
10	Q15	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD414		32.6℃	
11	Q12	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD412		32.8℃	
12					
13					
14					
15					

1. Operation Temperature (℃):
Ts = Defined by component specification ; Tm = Measured by QE

Note: The description in red states which temperature is over the specification of the device.

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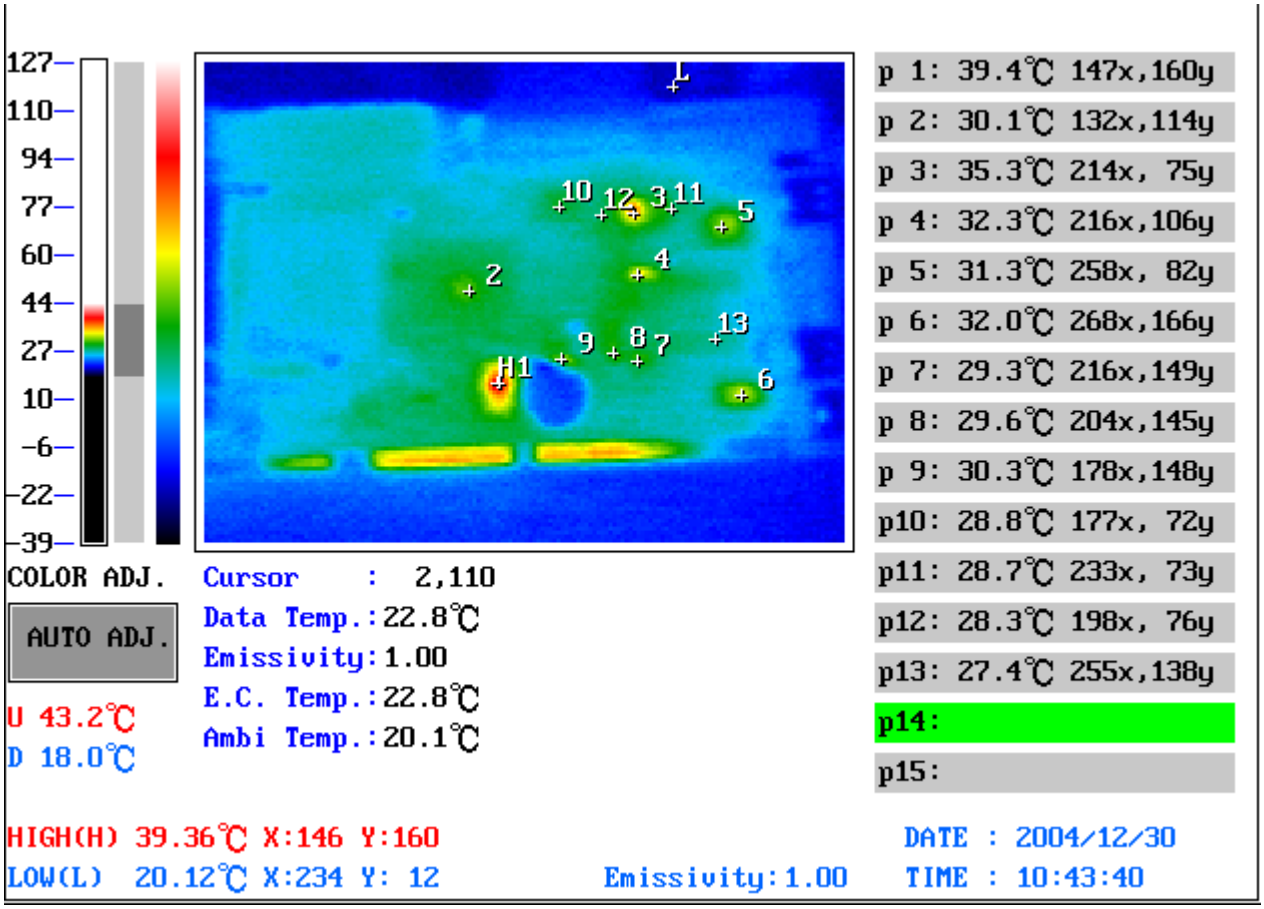
Thermal Image Analysis

Component Side –2:



Point	Position	Describe	Ts	Tm	Note
1	U45	IC.SMD.SSOP 48Pin Clock Generator.ICS.ICS952607		39.4℃	
2	U43	IC.SMD.Chipset ICH4.INTEL.FW82801DB SL6DM		30.1℃	
3	U47	IC.SMDSOT-23.4.38VSupervisoryCircuits.ANALOG DEVICE.ADM809MART		35.3℃	
4	U23	FLASH PLCC BIOS.256K.CS:932Eh.		32.3℃	
5	U19	IC.SMD BGA 196P.GigaBit Ethernet Chipset.INTEL.RC82541GI		31.3℃	
6	U22	IC.SMD.SSOP48 Chipset.INTEL.DA82562ET		32.0℃	
7	Q1	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD412		29.3℃	
8	Q2	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD412		29.6℃	
9	Q6	PWR.SMD.TO-252 N-Channel PowerMosfet.AOS.AOD412		30.3℃	
10	U34	IC.SMD.QFP128P Super I/O.ITE.IT8712F/HX		28.8℃	
11	U29	IC.SMDSSOP.RS232 Driver ESD 15KV.INTERSIL.HIN213ECA-T		28.7℃	
12	U33	IC.SMD.28Pin QSOP Parallel Term.CMD.Super 1284-04Q		28.3℃	
13	U24	IC.SMD PQFP.160P PCI to ISA Bridge Chip.ITE.IT8888F		27.4℃	
14					
15		The Room Temperature		20.8℃	

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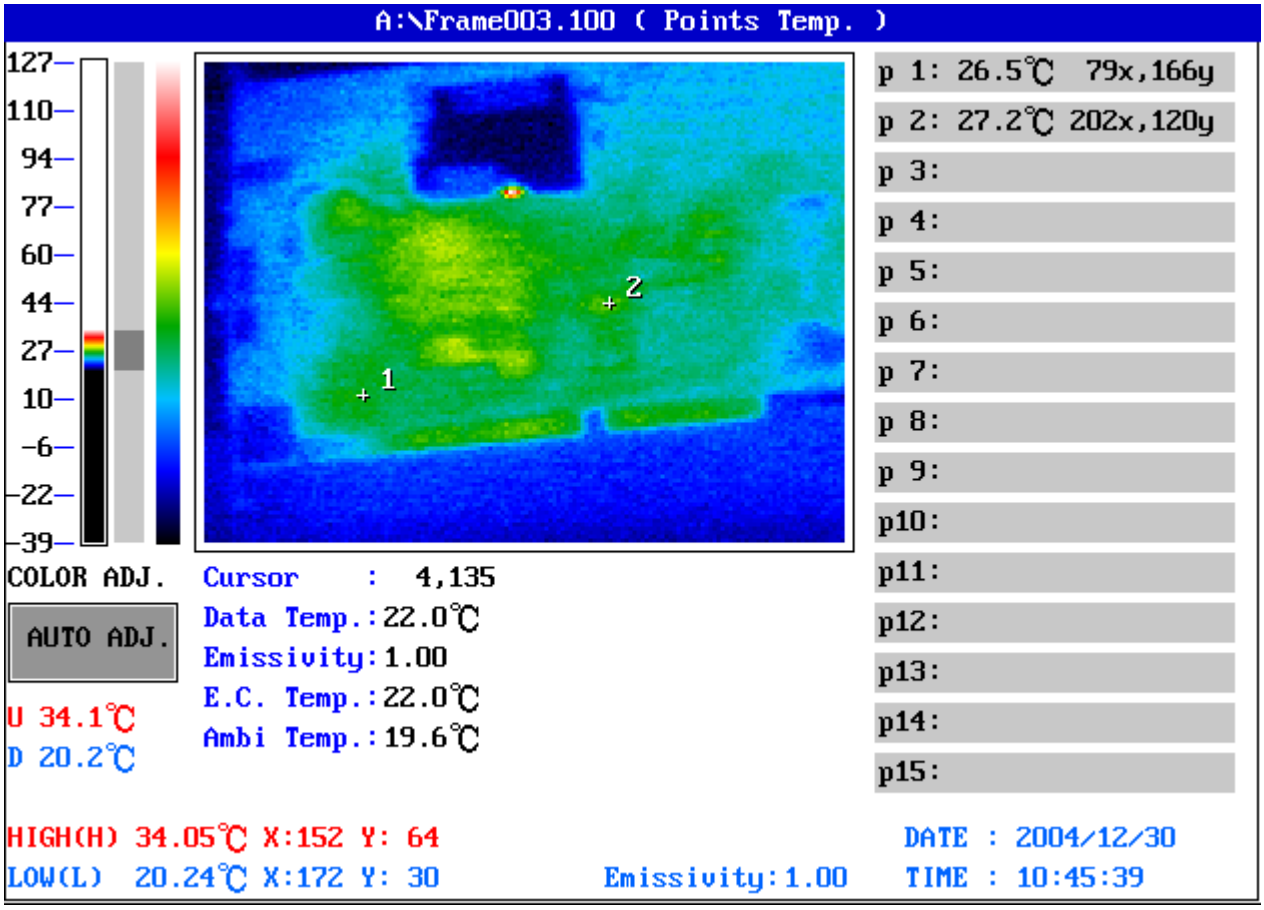
Component Side – 3:



Point	Position	Describe	Ts	Tm	Note
1	Y2	X'TAL SMD.25.000000MHz.6*3.5*1.1mm.2P.亞陶.F62500007		26.5℃	
2	R319	CR.8.2K.1/10W.5%.0603.SMD		27.2℃	
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12					
13					
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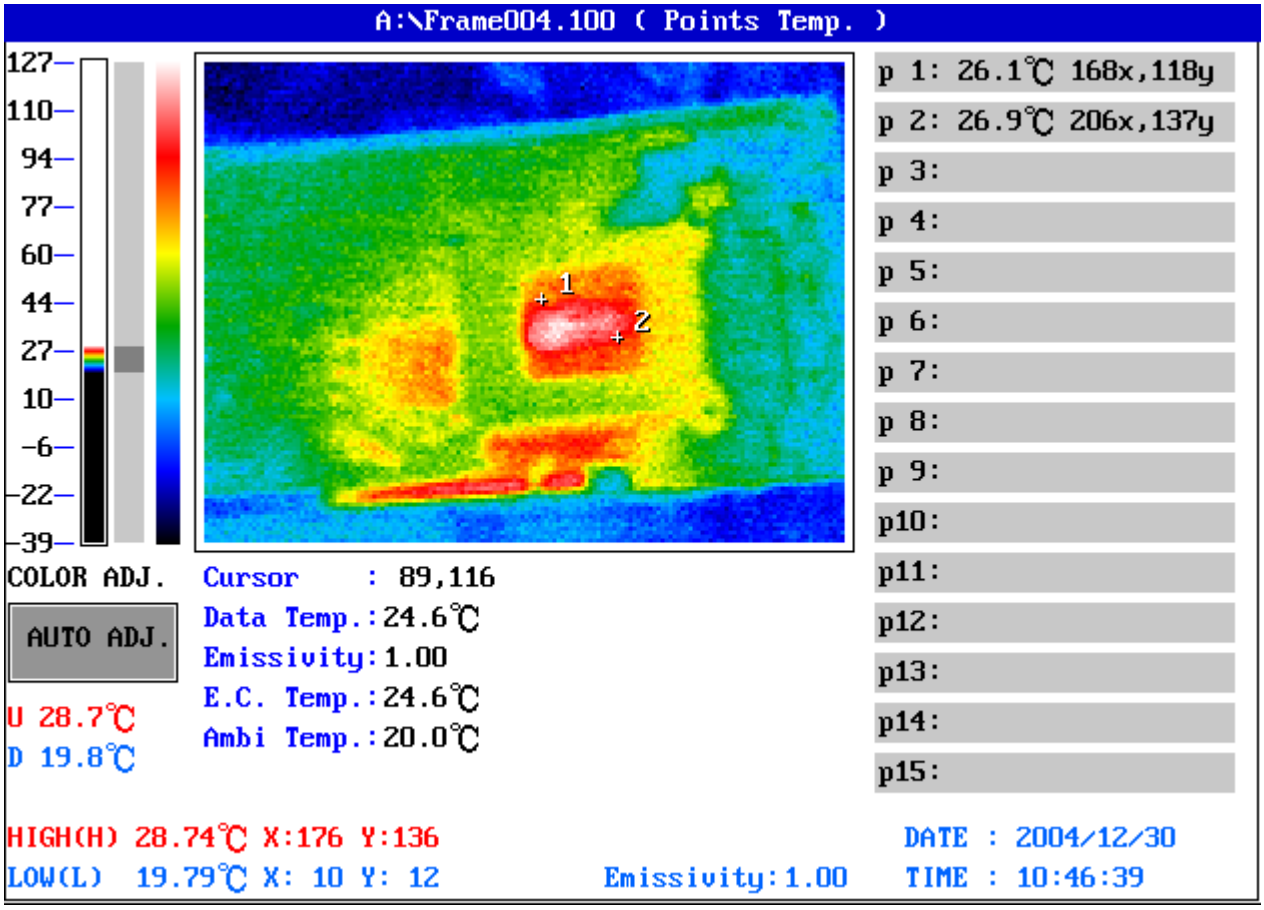
Component Side – 4:



Point	Position	Describe	Ts	Tm	Note
1	R468	CR.8.2K.1/10W.5%.0603.SMD		26.1℃	
2	R477	CR.300.1/10W.1%.0603.SMD		26.9℃	
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